

Serial No. **09/836,182**
Amendment

REMARKS

Applicants have amended Claim 14 to incorporate the subject matter of Claim 15 and clarify the present invention.

Initially, Applicants note that the Office Action, in paragraph 13 of the Office Action Summary, indicates that no certified copies of Applicants' priority document has been received. The priority document was filed in grandparent application, Serial No. 09/123,540, filed July 28, 1998, and thus carried on through the present division application. Notification of such filing is respectfully requested.

Applicants' invention, as now claimed, is to a semiconductor device having a semiconductor chip, a tape for mounting the semiconductor chip thereto, an adhesive resin layer interposed between the semiconductor chip and the tape, and solder balls arranged on the tape. The tape is of a material having a high water permeability of $10 \text{ g/m}^2 \cdot 24\text{H}$ or more, which is sufficient to prevent cracking and bulging of the semiconductor device which might occur when the solder balls are reflowed after the semiconductor device absorbs moisture. Such a semiconductor device is not taught or suggested in the cited prior art.

Reconsideration and removal of the rejection of Claim 14, as now amended, as anticipated by or obvious in view of Aoki et al. (U.S. 5,672,912) or as obvious in view of a combination of Aoki et al. and Suzuki et al. (U.S. 6,218,022) are respectfully requested in view of the present amendment and the following remarks.